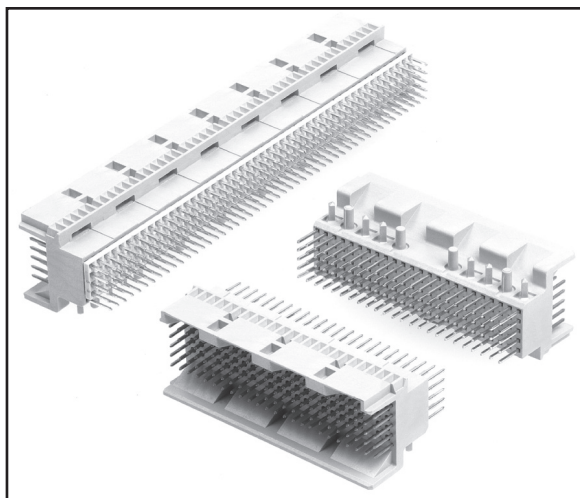


3M™ MetPak™ 2-FB Inverse Header

2 mm 5-Row, Stacking, Solder or Press-Fit Tail

MP2 Series



- 16 mm to 18.5 mm high-profile stacking
- Pin counts up to 300
- Footprint compatible with standard Futurebus+®
- Ideal for hot swapping applications
- End-to-end stackable
- Mates with MP2-R Series for parallel stacking applications
- See the Regulatory Information Appendix (RIA) in the “RoHS compliance” section of www.3Mconnector.com for compliance information (RIA E1 & C1 apply)

Date Modified: May 11, 2010

TS-1123-B
Sheet 1 of 4

Physical

Insulation:

Material: High Temp LCP
Flammability: UL 94V-0
Color: Beige

Contact:

Material: Copper Alloy

Plating:

Underplating: 50 μ " [1.27 μ m] Nickel
Wiping Area: See Ordering Information
Solder Tails: See Ordering Information

Electrical

Current Rating: Signal: 1.5 A – All contacts simultaneously

Insulation Resistance: 10^3 M Ω

Withstanding Voltage: 1000 V_{AC}

Environmental

Temperature Rating: -55°C to +125°C

Process Temperature Rating: 260°C (Profile per J-STD-020C)

Moisture Sensitivity Level: 1 (per J-STD-020C)

UL File No.: E68080

MetPak is a trademark of 3M Company.
Futurebus+ is a registered trademark of the Institute of Electrical and Electronic Engineers, Inc. (IEEE)

3M

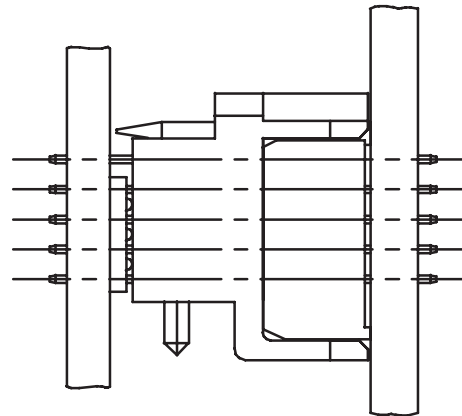
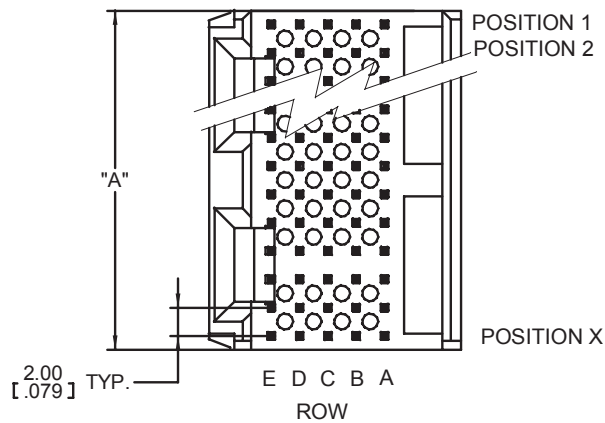
Electronic Solutions Division
Interconnect Solutions
<http://www.3Mconnector.com>

3M is a trademark of 3M Company.
For technical, sales or ordering information call
800-225-5373

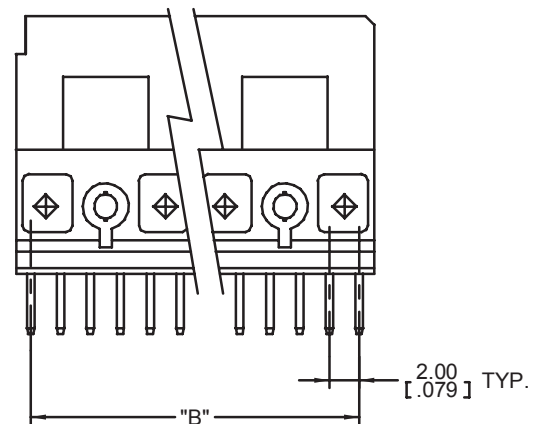
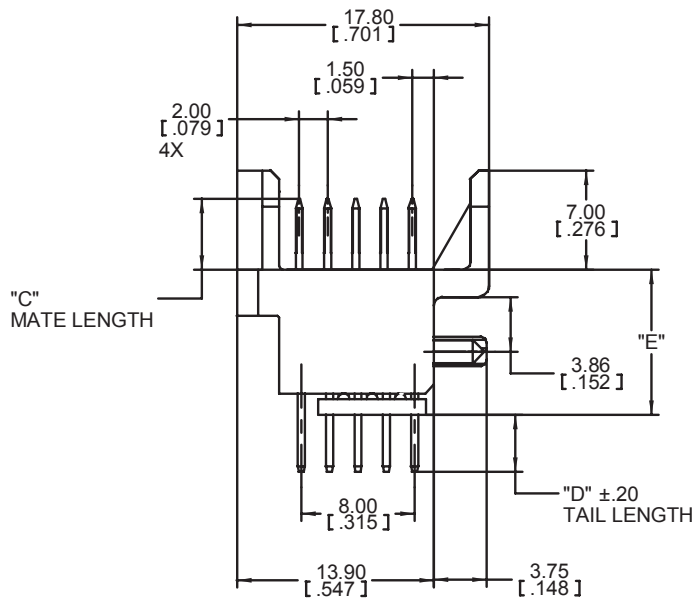
3M™ MetPak™ 2-FB Inverse Header

2 mm 5-Row, Stacking, Solder or Press-Fit Tail

MP2 Series



MATED WITH MP2-RXXX-5XXX-XXXX



mm
[inch]

Tolerance Unless Noted			
	0	0.0	0.00
mm	±3	±0.3	±0.13

[] Dimensions for Reference Only

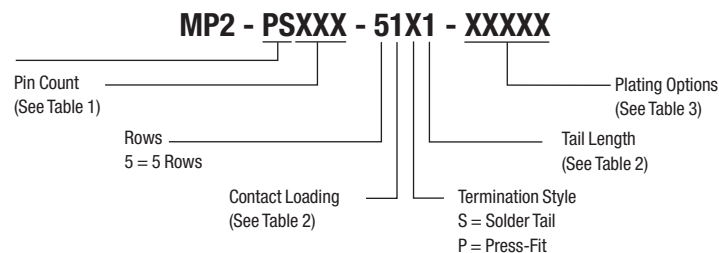
Notes:

1. Refer to IEC 61076-4-104 Futurebus+® global standard.
2. "Press Fit" describes a contact tail having a compliant section designed to make a reliable electrical connection with a plated through-hole (PTH) in a printed circuit board, typically a "back plane."
3. For special stack heights, tail lengths or pin arrangements, contact 3M.



Ordering Information

PS = Header, Inversed Stacking



TS-1123-B
Sheet 2 of 4



Electronic Solutions Division
Interconnect Solutions
<http://www.3Mconnector.com>

3M is a trademark of 3M Company.
For technical, sales or ordering information call
800-225-5373

3M™ MetPak™ 2-FB Inverse Header

2 mm 5-Row, Stacking, Solder or Press-Fit Tail

MP2 Series

Table 1 - Connector & Row Lengths

Pin Count	Dim. "A" mm [inch]	Dim "B" mm [inch]	Rows
030	11.95 [0.471]	10.00 [0.394]	5
060	23.95 [0.943]	22.00 [0.866]	5
090	35.95 [1.415]	34.00 [1.339]	5
120	47.95 [1.889]	46.00 [1.811]	5
150	59.95 [2.36]	58.00 [2.283]	5
180	71.95 [2.833]	70.00 [2.756]	5
210	83.95 [3.305]	82.00 [3.228]	5
240	95.95 [3.778]	94.00 [3.701]	5
270	107.95 [4.251]	106.00 [4.173]	5
300	119.95 [4.722]	118.00 [4.646]	5

Table 2

Contact-to-PC Board Tail Termination Option No.		Dim. "C"	Dim. "D"	Dim. "E"
Solder Tail	Press-Fit* Tail			
1		4.65 [0.183]	4.15 [0.163]	10.25 [0.404]
	1	5.00 [0.197]	3.95 [0.156]	10.25 [0.404]

Table 3 - Plating

Plating Suffix	Press-Fit Tails*	Solder Tails	Plating Composition
TG30	(RIA E2 & C2 apply)	(RIA E3 & C2 apply)	0.76 μ m [30 μ "] Min. Au Contact Area 2.54 μ m [100 μ "] Min. SnPb Tail Area 1.27 μ m [50 μ "] Min. Ni all over
TR30	(RIA E2 & C2 apply)	(RIA E3 & C2 apply)	0.08 μ m [3 μ "] Min. Au Contact Area 0.67 μ m [27 μ "] Min. PdNi Contact Area 2.54 μ m [100 μ "] Min. SnPb Tail Area 1.27 μ m [50 μ "] Min. Ni all over
KR	(RIA E1 & C1 apply)	(RIA E1 & C1 apply)	0.76 μ m [30 μ "] Min. Au Contact Area 2.54 μ m [100 μ "] Min. Matt Whisker Mitigating Sn Tail Area 1.27 μ m [50 μ "] Min. Ni all over
LR	(RIA E1 & C1 apply)	(RIA E1 & C1 apply)	0.08 μ m [3 μ "] Min. Au Contact Area 0.67 μ m [27 μ "] Min. PdNi Contact Area 2.54 μ m [100 μ "] Min. Matt Whisker Mitigating Sn Tail Area 1.27 μ m [50 μ "] Min. Ni all over

*Compliant-Pin Tail

TS-1123-B
Sheet 3 of 4



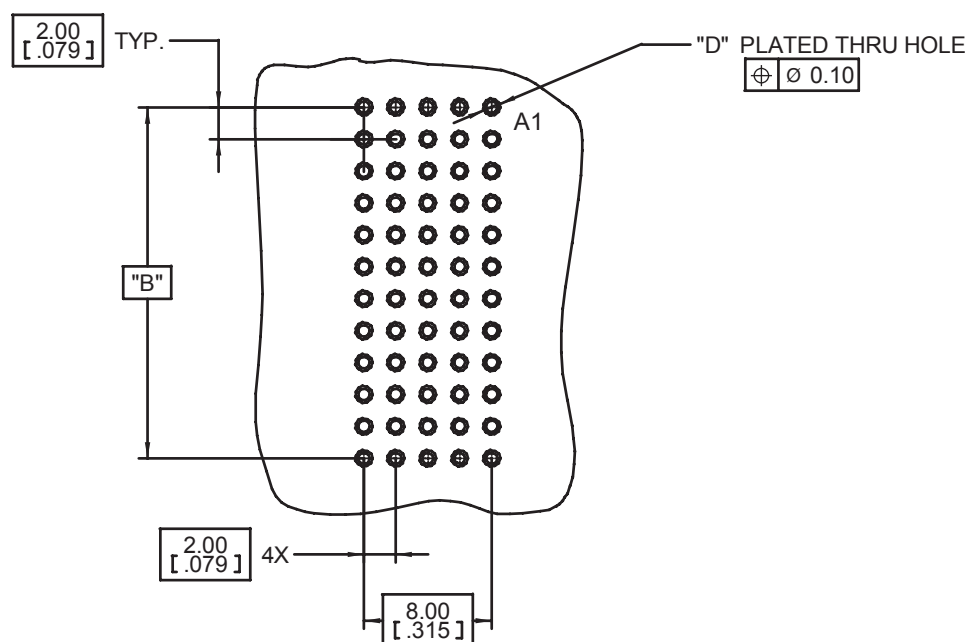
Electronic Solutions Division
Interconnect Solutions
<http://www.3Mconnector.com>

3M is a trademark of 3M Company.
For technical, sales or ordering information call
800-225-5373

3M™ MetPak™ 2-FB Inverse Header

2 mm 5-Row, Stacking, Solder or Press-Fit Tail

MP2 Series



RECOMMENDED PCB HOLE MOUNTING PATTERN

Table 4 – HOLE PLATING For TG30 and TR30 FINISHES ONLY

HOLE	Finished Dia. MM [in]	Cu Thickness [mm [in]	SnPb Thickness microns [μ"]	Drilled Hole Dia. mm [in]
"D"	0.65-0.80 [.0256-.0315]	0.025 [.001] min.	15 [600] max.	0.81-0.86 [.0319-.0339]

Table 5 – HOLE PLATING For KR and LR FINISHES ONLY

HOLE	Finished Dia. MM [in]	Cu Thickness [mm [in]	Immersion Matte Sn Thickness microns [μ"]	Electrolytic Au Thickness microns [μ"]	OSP ENTEK Thickness microns [μ"]	Drilled Hole Dia. mm [in]
"D"	0.700-0.800 [.0276-.0315]	0.025-0.045 [0.001-0.002]	0.5 - 2.5 [20 - 100]	0.1 - 0.5 [4 - 20]	0.2 - 0.5 [8 - 20]	0.830-0.860 [.0330-.0340] or 0.85 mm [#66] TWIST DRILL

TS-1123-B
Sheet 4 of 4



Electronic Solutions Division
Interconnect Solutions
<http://www.3Mconnector.com>

3M is a trademark of 3M Company.
For technical, sales or ordering information call
800-225-5373

Important Notice

All statements, technical information, and recommendations related to 3M's products are based on information believed to be reliable, but the accuracy or completeness is not guaranteed. Before using this product, you must evaluate it and determine if it is suitable for your intended application. You assume all risks and liability associated with such use. Any statements related to the product which are not contained in 3M's current publications, or any contrary statements contained on your purchase order shall have no force or effect unless expressly agreed upon, in writing, by an authorized officer of 3M.

Warranty; Limited Remedy; Limited Liability.

This product will be free from defects in material and manufacture for a period of ninety (90) days from the time of purchase. **3M MAKES NO OTHER WARRANTIES INCLUDING, BUT NOT LIMITED TO, ANY IMPLIED WARRANTY OF MERCHANTABILITY OR FITNESS FOR A PARTICULAR PURPOSE.** If this product is defective within the warranty period stated above, your exclusive remedy shall be, at 3M's option, to replace or repair the 3M product or refund the purchase price of the 3M product. **Except where prohibited by law, 3M will not be liable for any indirect, special, incidental or consequential loss or damage arising from this 3M product, regardless of the legal theory asserted.**



3M Electronics Solutions Division

6801 River Place Blvd.
Austin, TX 78726-9000
U.S.A.
1-800-225-5373
www.3Mconnector.com

Please recycle. Printed in USA.
© 3M 2010. All rights reserved.
RIA-2217B-E

3M is a trademark of 3M Company.

Данный компонент на территории Российской Федерации

Вы можете приобрести в компании MosChip.

Для оперативного оформления запроса Вам необходимо перейти по данной ссылке:

<http://moschip.ru/get-element>

Вы можете разместить у нас заказ для любого Вашего проекта, будь то серийное производство или разработка единичного прибора.

В нашем ассортименте представлены ведущие мировые производители активных и пассивных электронных компонентов.

Нашей специализацией является поставка электронной компонентной базы двойного назначения, продукции таких производителей как XILINX, Intel (ex.ALTERA), Vicor, Microchip, Texas Instruments, Analog Devices, Mini-Circuits, Amphenol, Glenair.

Сотрудничество с глобальными дистрибьюторами электронных компонентов, предоставляет возможность заказывать и получать с международных складов практически любой перечень компонентов в оптимальные для Вас сроки.

На всех этапах разработки и производства наши партнеры могут получить квалифицированную поддержку опытных инженеров.

Система менеджмента качества компании отвечает требованиям в соответствии с ГОСТ Р ИСО 9001, ГОСТ РВ 0015-002 и ЭС РД 009

Офис по работе с юридическими лицами:

105318, г.Москва, ул.Щербаковская д.3, офис 1107, 1118, ДЦ «Щербаковский»

Телефон: +7 495 668-12-70 (многоканальный)

Факс: +7 495 668-12-70 (доб.304)

E-mail: info@moschip.ru

Skype отдела продаж:

moschip.ru

moschip.ru_4

moschip.ru_6

moschip.ru_9